

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1888	sputter and magnetron and "204". clas. and vacuum and pressure	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:10
L3	295	sputter and magnetron and "204". clas. and vacuum and pressure with (different or distinct or various or varied)	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:11
L4	26	sputter and magnetron and "204". clas. and vacuum and pressure with (different or distinct or various or varied) and (partition or divider or separator)	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:27
L5	451678	sputter sputtering deposition	US-PGPUB; USPAT	OR	ON	2007/04/26 09:28
L7	1043457	stage stages	US-PGPUB; USPAT	OR	ON	2007/04/26 09:28
L8	9066	5 with 7	US-PGPUB; USPAT	OR	ON	2007/04/26 09:29
L9	4214884	two	US-PGPUB; USPAT	OR	ON	2007/04/26 09:29
L10	151824	7 near2 9	US-PGPUB; USPAT	OR	ON	2007/04/26 09:30
L11	1723	8 and 10	US-PGPUB; USPAT	OR	ON	2007/04/26 09:31
L12	1991908	pressure pressures	US-PGPUB; USPAT	OR	ON	2007/04/26 09:32
L13	59192	7 with 12	US-PGPUB; USPAT	OR	ON	2007/04/26 09:32
L14	291	11 and 13	US-PGPUB; USPAT	OR	ON	2007/04/26 09:33
L15	39	8 same 10 same 13	US-PGPUB; USPAT	OR	ON	2007/04/26 09:33
S1	12310	process and film and substrate and "204".clas.	US-PGPUB; USPAT	ADJ	ON	2007/04/18 09:58
S2	2786	process and film and substrate and "204".clas. and magnetron and sputtering	US-PGPUB; USPAT	ADJ	ON	2007/02/12 14:00
S3	0	process and film and substrate and "204".clas. and magnetron and sputtering and ion an polish	US-PGPUB; USPAT	ADJ	ON	2007/04/16 14:59
S4	2498	process and film and substrate and "204".clas. and magnetron and sputtering and target	US-PGPUB; USPAT	ADJ	ON	2007/02/12 14:01
S6	1	(optical device) and (lithographic projection) and (multilayer system)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:22

## EAST Search History

S7	64	(optical device) and (lithographic projection)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:24
S8	2863	etching and magnet and substrate and target and plasma	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:27
S9	2787	etching and magnet and substrate and target and plasma and (device or apparatus)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:27
S10	98	sputter and magnetron and "204". clas. and krypton and substrate and target	US-PGPUB; USPAT	ADJ	ON	2007/04/16 15:00
S11	24	sputter and magnetron and "204". clas. and krypton and substrate and target and (multilayer or multiple layer)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:48
S12	10	sputter and magnetron and "204". clas. and krypton and substrate and target and (multilayer or multiple layer) and (silicon or si) and (molybdenum or mo)	US-PGPUB; USPAT	ADJ	ON	2007/04/16 16:10
S13	7	sputter and magnetron and ion beam and "204".clas. and krypton and substrate and target and (silicon or si) and (molybdenum or mo)	US-PGPUB; USPAT	ADJ	ON	2007/04/16 15:35
S14	22	sputter and magnetron and "204". clas. and krypton and substrate and target and ion and energy and (eV or electronvolt)	US-PGPUB; USPAT	ADJ	ON	2007/04/26 09:10
S15	5	sputter and magnetron and "204". clas. and krypton and substrate and target and ion and energy and (eV or electronvolt) and (molybdenum or Mo) and (silicon or Si)	US-PGPUB; USPAT	ADJ	ON	2007/04/16 16:39
S16	0	kawaguchi and 2003-83335	JPO	ADJ	ON	2007/04/16 16:40
S17	0	jp-200383335-\$.did.	JPO	ADJ	ON	2007/04/16 16:42
S18	0	jp-83335-\$.did.	JPO	ADJ	ON	2007/04/16 16:41
S19	0	kawaguchi and fujiki and gonda and tahara	JPO	ADJ	ON	2007/04/16 16:41
S20	1	JP2000383335.ap.	JPO	ADJ	ON	2007/04/16 16:45
S21	0	JP200383335.ap.	JPO	ADJ	ON	2007/04/16 16:44
S22	0	JP2003083335.ap.	JPO	ADJ	ON	2007/04/16 16:44
S23	0	JP0200383335.ap.	JPO	ADJ	ON	2007/04/16 16:44
S24	0	jp-83335-\$.did.	JPO	ADJ	ON	2007/04/16 16:45
S25	0	jp-0383335-\$.did.	JPO	ADJ	ON	2007/04/16 16:46

## EAST Search History

S26	0	JP-2003083335-\$.did. JP-2002063827-A.DID.	JPO	ADJ	ON	2007/04/16 16:47
S27	1	JP-2003083335-\$.did.	JPO	ADJ	ON	2007/04/16 16:47
S28	0	JP-200383335-\$.did.	JPO	ADJ	ON	2007/04/16 16:48
S29	0	JP-2003833350-\$.did.	JPO	ADJ	ON	2007/04/16 16:48
S30	0	JP-200383335-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2007/04/16 16:57
S31	21185	kawaguchi.in.	JPO	ADJ	ON	2007/04/16 16:57
S32	13	kawaguchi.in. and gonda.in.	JPO	ADJ	ON	2007/04/16 16:57
S33	0	kawaguchi.in. and gonda.in. and fujiki.in.	JPO	ADJ	ON	2007/04/16 16:58
S34	13	kawaguchi.in. and gonda.in.	JPO	ADJ	ON	2007/04/16 16:58
S35	596	"204".clas. and (mean free path)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:40
S36	454	"204".clas. and (mean free path) and apparatus	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:40
S37	14	sputter and magnetron and "204". clas. and krypton and substrate and target and (mean free path)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 08:48
S38	101	sputter and "204".clas. and (mean free path) with (small or smaller or less)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:21
S39	9	sputter and "204".clas. and (mean free path) with (small or smaller or less) and krypton	US-PGPUB; USPAT	ADJ	ON	2007/04/17 10:44
S40	12	ion and "204".clas. and (mean free path) with (small or smaller or less) and krypton	US-PGPUB; USPAT	ADJ	ON	2007/04/17 10:44
S41	0	donahue.in. and (Method of Sputtering using krypton)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S42	650	donahue.in.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:38
S43	0	(hilke donahue).in.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:38
S44	0	donohue.in. and (Method of Sputtering using krypton)	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S45	306	donohue.in.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S46	8	donohue.in. and "204".clas.	US-PGPUB; USPAT	ADJ	ON	2007/04/17 11:39
S47	1	("4923585").PN.	US-PGPUB; USPAT	OR	OFF	2007/04/17 17:31

## EAST Search History

S48	1	("20060081458").PN.	US-PGPUB; USPAT	OR	OFF	2007/04/18 10:47
S49	13	electron beam adj (vapor or evaporation)and "204".clas. and target and substrate and (mean free path)	US-PGPUB; USPAT	ADJ	ON	2007/04/18 10:48